



## Technical Data Sheet

<b>MATERIAL:</b>	Ethylene/vinyl acetate copolymer																
<b>CATALOG NUMBER:</b>	787																
<b>CAS NUMBER:</b>	24937-78-8																
<b>DESCRIPTION:</b>	Random copolymer of ethylene and vinyl acetate																
<b>FORMULA:</b>	$(C_4H_6O_2.C_2H_4)_x$																
<b>TYPICAL PROPERTIES:</b>	<table><tr><td>Appearance:</td><td>Beads</td></tr><tr><td>Vinyl acetate content:</td><td>40 wt%</td></tr><tr><td>Approx Mw:</td><td>200,000 [GPC]</td></tr><tr><td>Melt flow index:</td><td>2-5 g/10min</td></tr><tr><td>Mooney viscosity:</td><td>20 (100°C)</td></tr><tr><td>Density:</td><td>0.98</td></tr><tr><td>Melting point:</td><td>100°C</td></tr><tr><td>Solubility:</td><td>Benzene, dioxane, MEK, methylene chloride, THF, toluene, xylene</td></tr></table>	Appearance:	Beads	Vinyl acetate content:	40 wt%	Approx Mw:	200,000 [GPC]	Melt flow index:	2-5 g/10min	Mooney viscosity:	20 (100°C)	Density:	0.98	Melting point:	100°C	Solubility:	Benzene, dioxane, MEK, methylene chloride, THF, toluene, xylene
Appearance:	Beads																
Vinyl acetate content:	40 wt%																
Approx Mw:	200,000 [GPC]																
Melt flow index:	2-5 g/10min																
Mooney viscosity:	20 (100°C)																
Density:	0.98																
Melting point:	100°C																
Solubility:	Benzene, dioxane, MEK, methylene chloride, THF, toluene, xylene																
<b>GENERAL INFORMATION:</b>	Finds use primarily in hot melt coatings and adhesives. Imparts improved toughness, flexibility and adhesion to coating and adhesive formulations. Because of high vinyl acetate content, it is more soluble in organic solvents than other VA copolymers.																
<b>STRUCTURE:</b>																	

Technical information and data regarding the composition, properties or use of the products described herein is believed reliable. However, no representation or warranty is made with respect thereto except as made by Sp<sup>2</sup> in writing at time of sale. Sp<sup>2</sup> cannot assume responsibility for any patent liability which may arise from the use of any product in a process, manner or formula not designed by Sp<sup>2</sup>.